深圳市光得光科技有限公司

SAMPLE APPROVAL SHEET

DESCRIPTIONS:

- •3.2x1.6x0.8mm SMD LED
- • 物料代码 01.02.05.0028

CUSTOMER:_____

MASON P/N:C1206反贴白灯

CUSTOMER P/N:_____

CUSTOMER APPROVED SIGNATURES

APPROVRD BY	CHECKED BY

PRELIMINARY SPEC

3.2x1.6X0.8mm SMD CHIP LED

PART NO: C1206UW WHITE

ATTENTION

OBSERVE PRECAUTIONS FOR HANDLING LECTROSTATIC DISCHARGE SENSITIVE DEVICES

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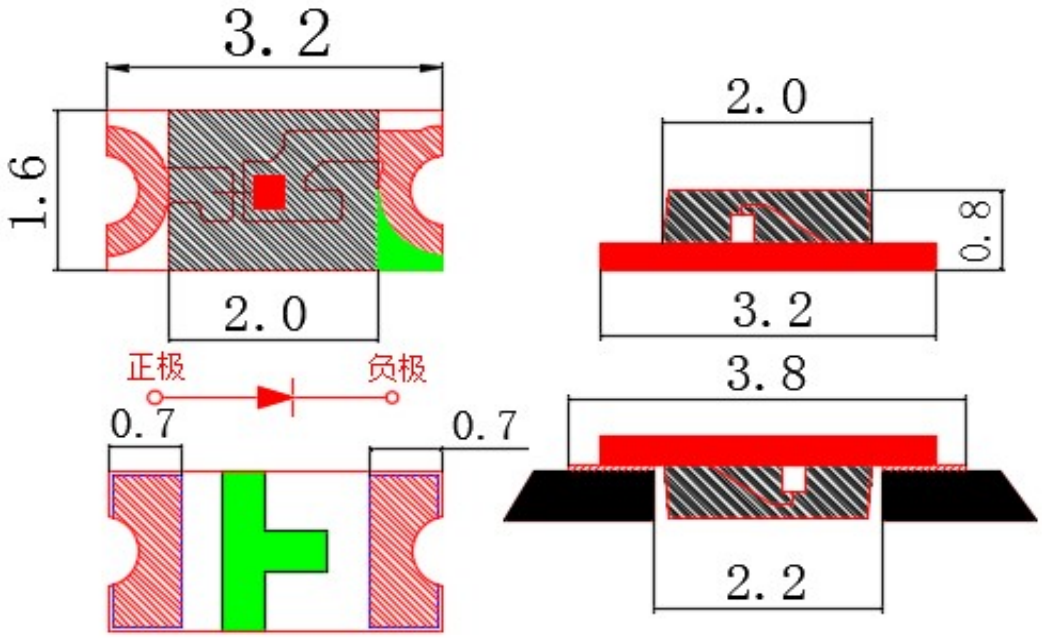
Features

- 3.2mmx1.6mm SMT LED, 0.8mm THICKNESS.
- WIDE VIEWING ANGLE.
- IDEAL FOR BACKLIGHT AND INDICATOR.
- PACKAGE : 3000PCS / REEL.
- RoHS COMPLIANT.

Applications

- Automotive: backlighting in dashboard and switch.
- Telecommunication: indicator and back-lighting in telephone and fax.
- Flat backlight for LCD switch and symbol.

◆ Package Dimensions



Notes:
1. All dimensions are in millimeters.
2. Tolerance is ±0.15 unless otherwise noted.
3. Specifications are subject to change without notice.

◆ Device Selection Guide

Part No.	Chip		Lens color
C1206UW	Material	Emitted color	Yellow Fluorescent
	(InGaN)	WHITE	

◆ Absolute Maximum Ratings at TA=25°C

Parameter	Symbol	Value	Unit

Power Dissipation	PD	100	mW
Forward Current	IF	20	mA
Peak Forward Current*1	IFP	100	mA
Reverse Voltage	VR	5	V
Operating Temperature	Topr	-40°C To +85°C	
Storage Temperature	Tstg	-40°C To +85°C	

Notes:
*1: Pulse width≤0.1ms, Duty cycle≤1/10

◆ Electrical / Optical Characteristics at TA=25°C

Parameter	Symbol	Min	typ	Max	Unit	Test Conditions
Forward Voltage	VF	2.6	—	3.2	V	IF=5mA
Reverse Current	IR	—	—	10	μA	VR=5V
Chromaticity Coordinates	X	—	0.27	—		IF=5mA
	Y	—	0.28	—		
Luminous Intensity	IV	200	—	500	mcd	IF=5mA
Viewing Angle	2θ1/2	—	120	—	Deg.	IF=5mA

Remarks:
If special sorting is required (e.g. binning based on forward voltage, luminous intensity, or chromaticity), the typical accuracy of the sorting process is as follows:
1. Chromaticity Coordinates: ±0.01
2. Luminous Intensity: ±15%
3. Forward Voltage: ±0.1V

◆ Typical Electrical/Optical Characteristics Curves

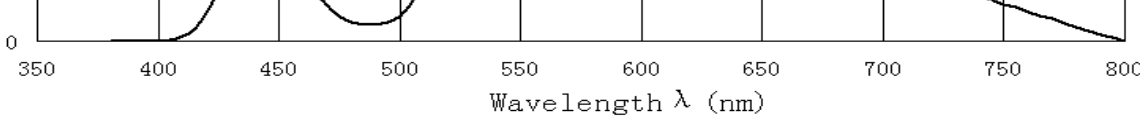


Fig. 1 Relative Intensity vs. Wavelength

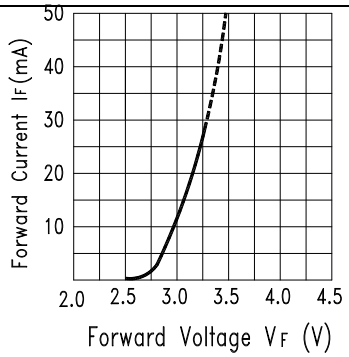


Fig.2 Forward Current vs. Forward Voltage

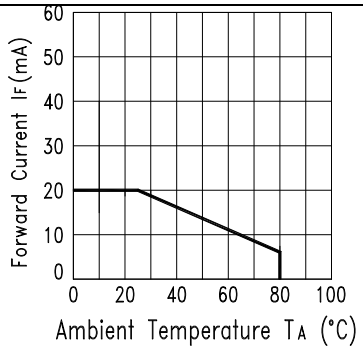


Fig.3 Forward Current Derating Curve

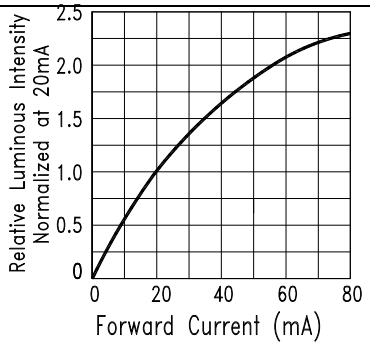


Fig.4 Relative Luminous Intensity vs. Forward Current

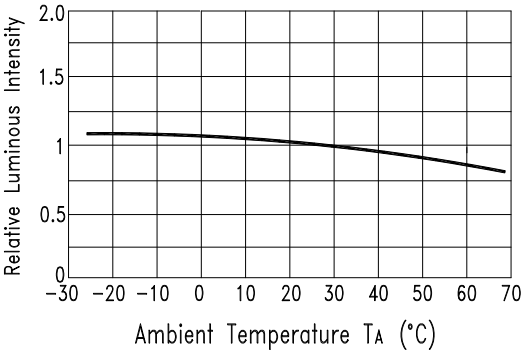


Fig.5 Luminous Intensity vs.Ambient Temperature

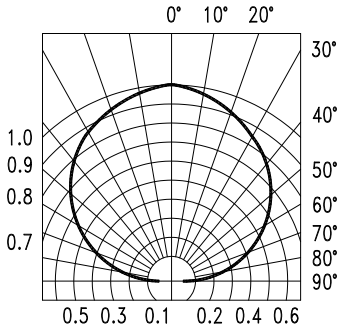
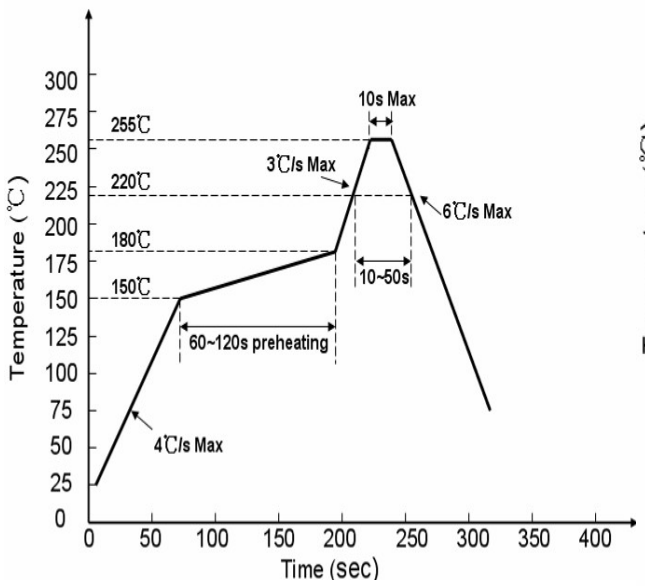
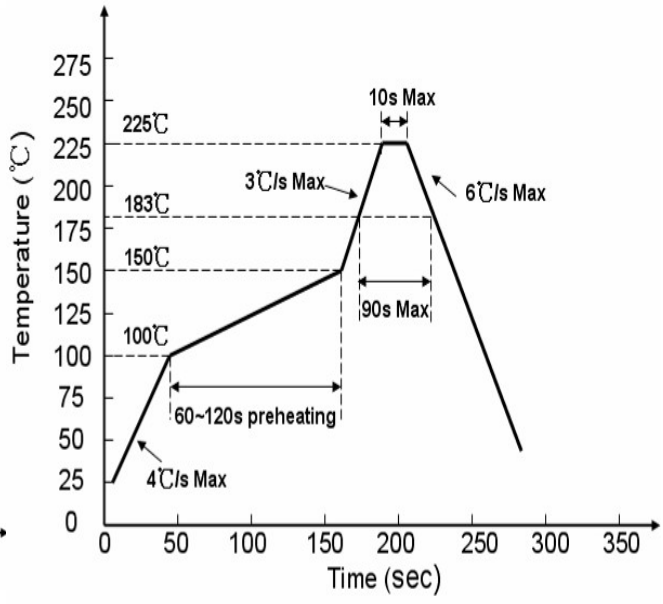


Fig.6 Spatial Distribution

◆ Soldering Profile



Lead process



Lead process

◆ Tape specifications

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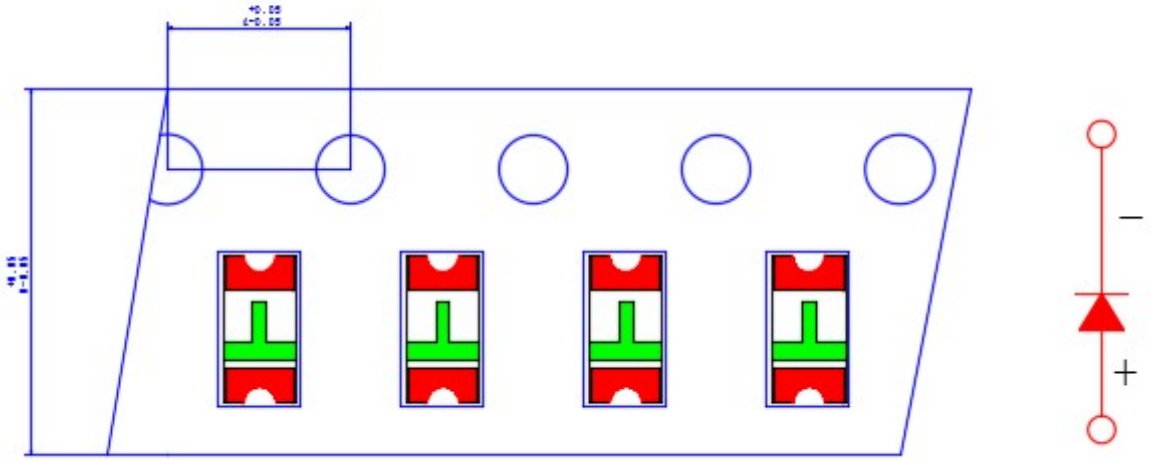
(Units:mm)

1206反编带方式



◆ VF Rank

Rank		VF		Condition
		MIN	MAX	
b	b2			IF=5mA
	b3	2.7	2.8	
	b4	2.8	2.9	
	b5	2.9	3.0	
c	c1	3.0	3.1	
	c2	3.1	3.2	

Tolerance:±0.05V

◆ IV Rank

Rank		IV		Condition
		MIN	MAX	
p	p1	160	200	IF=5mA

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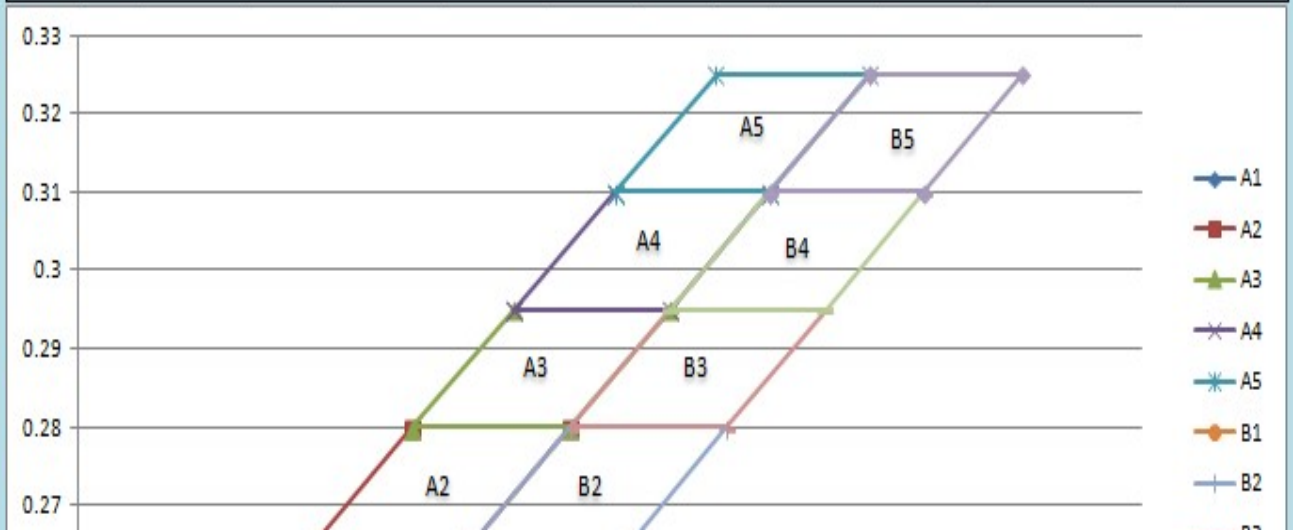
	p2	200	250	
q	q1	250	300	
	q2	300	350	
r	r1	350	400	
	r2			

Tolerance:±15%

◆ **X Y Rank**

A1	X	0.25	0.2576	0.2695	0.262	0.25	B1	X	0.262	0.2695	0.2814	0.274	0.262
	Y	0.25	0.265	0.265	0.25	0.25		Y	0.25	0.265	0.265	0.25	0.25
A2	X	0.2576	0.2652	0.277	0.2695	0.2576	B2	X	0.2695	0.277	0.2888	0.2814	0.2695
	Y	0.265	0.28	0.28	0.265	0.265		Y	0.265	0.28	0.28	0.265	0.265
A3	X	0.2652	0.2728	0.2845	0.277	0.2652	B3	X	0.277	0.2845	0.2962	0.2888	0.277
	Y	0.28	0.295	0.295	0.28	0.28		Y	0.28	0.295	0.295	0.28	0.28
A4	X	0.2728	0.2804	0.292	0.2845	0.2728	B4	X	0.2845	0.292	0.3036	0.2962	0.2845
	Y	0.295	0.31	0.31	0.295	0.295		Y	0.295	0.31	0.31	0.295	0.295
A5	X	0.2804	0.288	0.2995	0.292	0.2804	B5	X	0.292	0.2995	0.311	0.3036	0.292
	Y	0.31	0.325	0.325	0.31	0.31		Y	0.31	0.325	0.325	0.31	0.31



Tolerance:±0.01

◆Judgment criteria of failure for the reliability

Measuring items	Symbol	Measuring conditions	Judgement criteria for failure
Forward voltage	V_F(V)	I_F=5mA	Initial Level*1.1
Reverse current	I_R(UA)	V_R=5V	Over U*2
Luminous intensity	IV(mcd)	I_F=5mA	Initial Level*0.7

◆ **CAUTIONS:**

1.Storage

• In order to avoid the absorption of moisture, it is recommended to store in the dry box (or desicca tor) with a desiccant. Otherwise, to store them in the following environment is recommended. Temperature: 5°C~30°CHumidity: 60%HR max.

• Attention after opened

However LED is corresponded SMD, when LED be soldered dip, interfacial separation may affect The light transmission efficiency, causing the light intensity to drop. Attention in followed. a. After opened and mounted, the soldering shall be quickly. b. Keeping of a fraction Temperature: 5°C~40°C Humidity: less than 30%

• In case or more than 1 week passed after opening or change color of indicator on desiccant compo nents shall be dried 10-12hr. at 60°C±3°C.

• In case of supposed the components is humid, shall not be dried dip-solder just before. 100Hr at 80°C±3°C or 12Hr at 100°C±3°C

2.ESD (Electrostatic Discharge)

Static Electricity or power surge will damage the LED.

The following procedures may decrease the possibility of ESD damage.

• All production machinery and test instruments must be electrically grounded.

• Use a conductive wrist band or anti-electrostatic glove when handling these LEDs.

• Maintain a humidity level of 50% or higher in production areas.

• Use anti-static packaging for transport and storage.